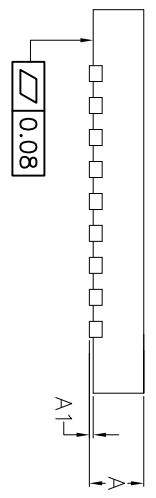
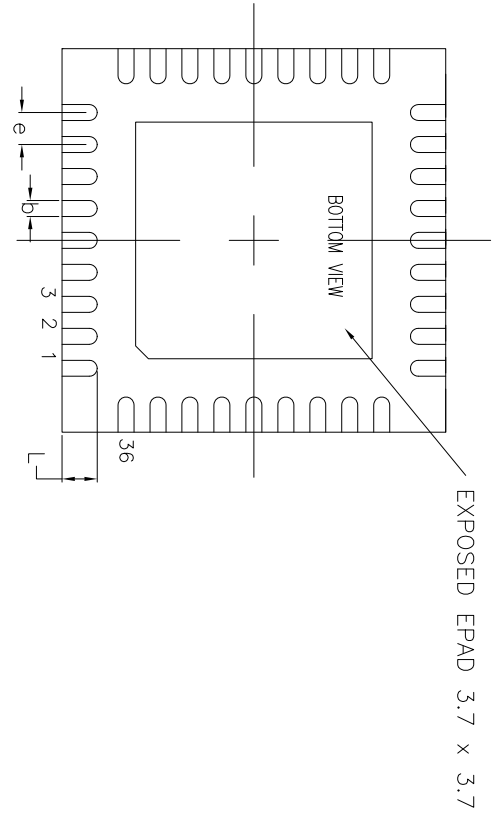
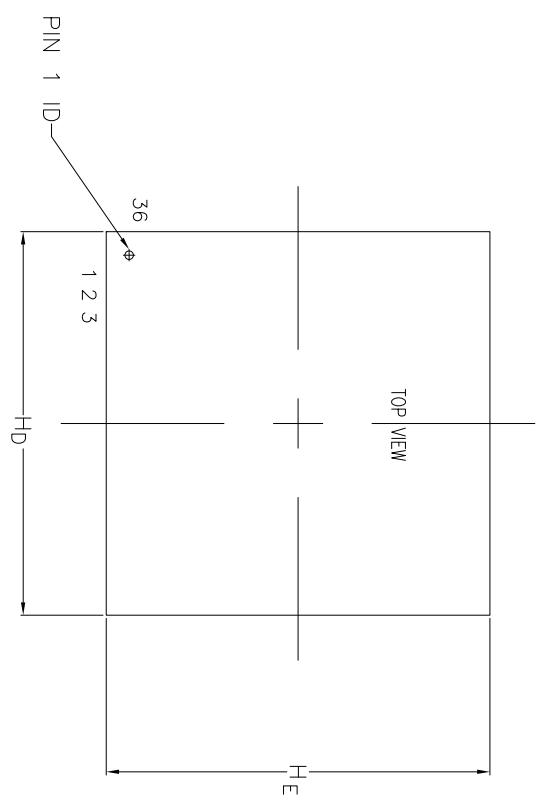


REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
00	INITIAL RELEASE	2/23/16	JHUJA

BASED ON JEDEC MO-220
 1. DIMENSIONS (IN MILLIMETERS)



- 2. WEIGHT <0.1 g
- 3. PACKAGE BODY MATERIAL LOW STRESS EPOXY
- 4. LEAD MATERIAL Cu-ALLOY
- 5. LEAD FINISH SOLDER PLATING

DIMENSIONS	min	max
A	0.8	0.9
A1	0	0.05
b	0.2	0.3
e	0.5	nom
Hd	5.9	6.1
HE	5.9	6.1
L	0.45	0.65

TOLERANCES UNLESS SPECIFIED		DECIMAL ANGULAR	
XXX	±	XXX	±
XXXX		XXXX	
APPROVALS	DATE	TITLE	
DRAWN: DAC	12/23/16	NLG36 PACKAGE OUTLINE	
CHECKED		6.0 x 6.0 mm BODY, EPAD 3.7 x 3.7	
		0.50 mm PITCH QFN	
DO NOT SCALE DRAWING	SIZE C	DRAWING No. PSC-4648-01	REV 00
SHEET 1 OF 1			

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